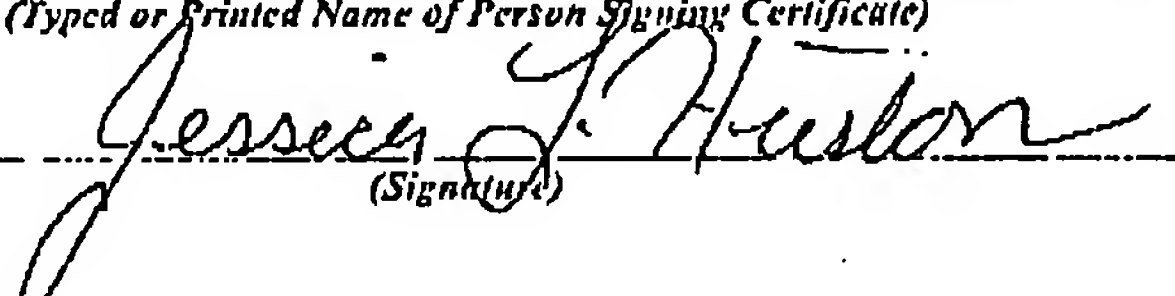


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<b>CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)</b>			<b>Docket No.</b>
Applicant(s): <b>ROGER LAM ET AL.</b>			<b>FIS920030398US1</b>
<b>Application No.</b> 10/708,066	<b>Filing Date</b> 02/06/2004	<b>Examiner</b> B. CHERVINSKY	<b>Group Art Unit</b> 2835
<b>Invention: METHOD AND STRUCTURE FOR HEAT SINK ATTACHMENT IN SEMICONDUCTOR DEVICE PACKAGING</b>			
<p>I hereby certify that this <u>Notice of Appeal and Pre-Appeal Brief Request for Review</u> (Identify type of correspondence) is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. 571-273-8300) on <u>11/03/2005</u> (Date)</p> <p style="text-align: right;"><u>Jessica L. Huston</u> (Typed or Printed Name of Person Signing Certificate)  (Signature)</p> <p style="text-align: center;">Note: Each paper must have its own certificate of mailing.</p>			

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